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S3	3	BRAND-MICHAEL-J.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/12/23 18:21
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S6	1	MCLEAN-HARRY-W.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/12/23 18:22
S7	0	(S3 S4 S5 S6) and (mtbf)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/12/23 18:23
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S28	4	S27 and exponent\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/12/23 20:00
S29	5	S27 and exponent\$5	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/12/23 20:00
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1 Accelerated stress testing for both hardware and software
Chan, H.A.;

Reliability and Maintainability, 2004 Annual Symposium - RAMS , 2004

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2 Accelerated stress testing to detect probabilistic software failures
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3 Guidelines for physics-of-failure based accelerated stress testing
Upadhyayula, K.; Dasgupta, A.;

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4 Long-term testing in a short-term world
Rokosz, V.T.;

Software, IEEE , Volume: 20 , Issue: 3 , May-June 2003

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5 Qualification testing procedures for amorphous silicon modules

Ross, R.; Call, J.; Vogeli, C.; Nath, P.;
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6 Comparison of delamination effects between temperature cycling test and highly accelerated stress test, in plastic packaged devices
van Gestel, R.; de Zeeuw, K.; van Gemert, L.; Bagerman, E.;
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8 Silicon ultrasonic horns for thin film accelerated stress testing
Chung-Hoon Lee; Lal, A.;
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Pages:867 - 870 vol.2

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9 Improving gold-silver wirebond integrity in plastic packages
Sow, Y.K.; Yasmin, A.; Dias, R.;
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10 Mercury porosimetry investigation of plastic, integrated circuit packages
Perreault, G.C.; Thornton, A.W.;
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March-2 April 1992
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11 Investigation of ultrasonic flip chip bonding on flex substrates
Schafer, H.; Yuan, P.; Wang, Z.P.;
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12 Highly accelerated stress test (HAST) for low-cost flip chip on b ar technology

Jianzhong Wei; Qunyong Wang; Wen Luo; Guowei Xiao; Chan, P.C.H.;
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14 Package related reliability investigation with a multi-sensor chip

van Gestel, R.; van Gemert, L.; Bagerman, E.;
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15 Reliability qualification of a demountable packaging technology

Matta, F.; Afshari, B.; Pendse, R.; Karnezos, M.;
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... and the relatively new Highly **Accelerated Stress Test** (HAST) have ... is based upon the **exponential** distribution model ... Mean Time Between Failure (**MTBF**) are shown ...

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... Time to Failure (MTTF or **MTBF**) and useful ... 0 1/ 2/ 3/ t Figure 4. **Exponential** Distribution ...

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... Mean Time to Failure (MTTF) or Mean Time Between Failures (**MTBF**) ... to various failure mechanisms (Normal, Lognormal, Weibull, and **Exponential** distributions are ...

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 23 May 1990

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